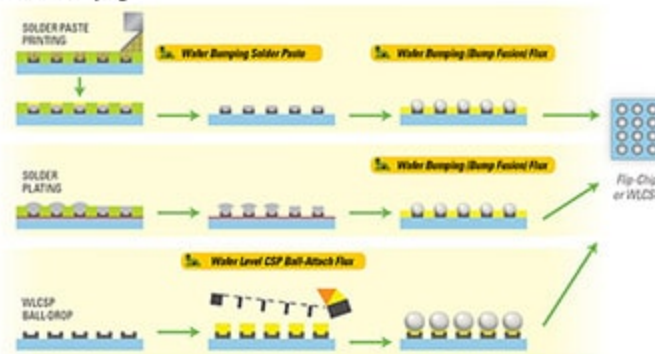
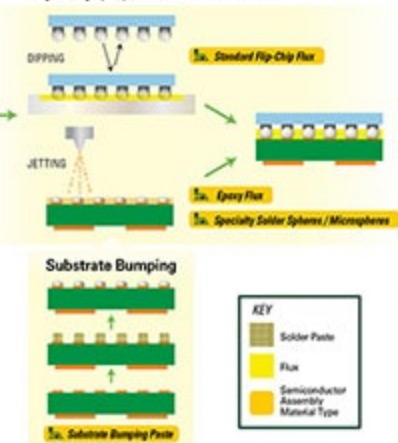


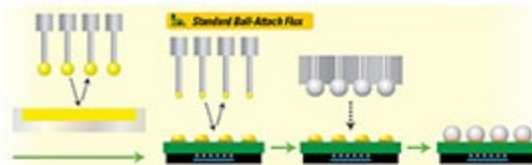
### Wafer Bumping



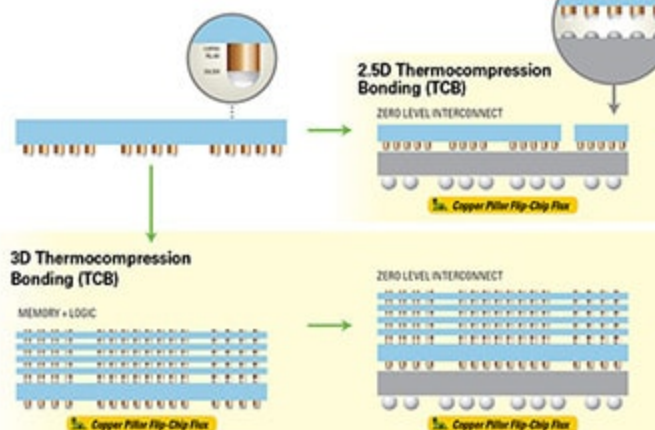
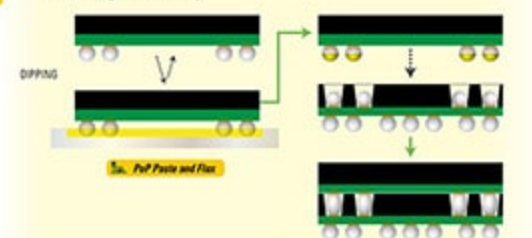
### Flip-Chip (C4) or Wafer Level CSP



### Ball-Attach



### PoP Package Assembly



*Critical characteristics of many semiconductor assembly materials:*

- Environmentally benign
- No-clean
  - Ultra-low residue
- Water soluble
  - Residues soluble in deionized water
- Ultra-low alpha emissions
- Halogen levels
  - Low halogen / No intentionally-added halogen
- Long usage life
- Low voids
- Colored / UV-dye
- Semiconductor grade

**INDIUM CORPORATION**